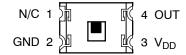


- Converts Light Intensity to Output Voltage
- Monolithic Silicon IC Containing Photodiode, Transconductance Amplifier, and Feedback Components
- Single-Supply Operation . . . 2.7 V to 5.5 V
- High Irradiance Responsivity . . . Typical 96 mV/(μW/cm²) at λ_p = 640 nm (TSL12T)
- Low Supply Current . . . 1.1 mA Typical
- Low-Profile Surface-Mount Package
- RoHS Compliant

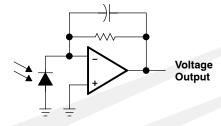
PACKAGE T 4-LEAD SMD (TOP VIEW)



Description

The TSL12T and TSL13T are cost-optimized, highly integrated light-to-voltage optical sensors, each combining a photodiode and a transimpedance amplifier (feedback resistor = $80~M\Omega$ and $20~M\Omega$, respectively) on a single monolithic integrated circuit. The photodiode active area is $0.5~mm \times 0.5~mm$ and the sensors respond to light in the range of 320 nm to 1050 nm. Output voltage is linear with light intensity (irradiance) incident on the sensor over a wide dynamic range. These devices are supplied in a low-profile surface-mount package (T).

Functional Block Diagram



Available Options

| DEVICE | TA | PACKAGE - LEADS | PACKAGE DESIGNATOR | ORDERING NUMBER |
|--------|------------|----------------------------------|--------------------|-----------------|
| TSL12 | 0°C to 70° | 4-lead Low-Profile Surface-Mount | \ T | TSL12T |
| TSL13 | 0°C to 70° | 4-lead Low-Profile Surface-Mount | T | TSL13T |

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TSL12T, TSL13T LIGHT-TO-VOLTAGE CONVERTERS

TAOS062D - APRIL 2007

Terminal Functions

| TERMINAL | | | |
|----------|--------------|--|--|
| NAME | T PKG NO. | DESCRIPTION | |
| GND | 2 | Power supply ground (substrate). All voltages are referenced to GND. | |
| OUT | 4 | Output voltage. | |
| V_{DD} | 3 | Supply voltage. | |
| N/C | 1 | No connection. | |

Absolute Maximum Ratings over operating free-air temperature range (unless otherwise noted)[†]

| Supply voltage, V _{DD} (see Note 1) | 6 V |
|--|---------------|
| Output current, I _O | ±10 mA |
| Duration of short-circuit current at (or below) 25°C (see Note 2) | 5 s |
| Operating free-air temperature range, T _A | -25°C to 85°C |
| Storage temperature range, T _{stg} | -25°C to 85°C |
| Solder conditions in accordance with JEDEC J-STD-020A, maximum temperature | 260°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to GND.

2. Output may be shorted to supply.

Recommended Operating Conditions

| | MIN | NOM MAX | UNIT |
|--|-----|---------|------|
| Supply voltage, V _{DD} | 2.7 | 5.5 | V |
| Operating free-air temperature, T _A | 0 | 70 | °C |



Electrical Characteristics at V_{DD} = 5 V, T_A = 25°C, λ_p = 640 nm, R_L = 10 k Ω (unless otherwise noted) (see Notes 3, 4, 5)

| PARAMETER | | TEGT CONDITIONS | TSL12T | | | TSL13T | | | | |
|-----------------|-----------------------------|-------------------------------|--------|------|----------|--------|------|------|----------------------------------|--|
| | | TEST CONDITIONS | MIN | TYP | MAX | MIN | TYP | MAX | UNIT | |
| V_{OM} | Maximum output voltage | | 4.6 | 4.9 | | 4.6 | 4.9 | | V | |
| | | $E_e = 20.5 \ \mu W/cm^2$ | 1.5 | 2 | 2.5 | | | | | |
| l., | Output voltage | $E_e = 83 \mu W/cm^2$ | | | | 1.5 | 2 | 2.5 | | |
| Vo | | $E_e = 41 \mu W/cm^2$ | | 4 | | | | | V | |
| | | $E_e = 166 \mu\text{W/cm}^2$ | | | | | 4 | | | |
| R _e | Irradiance responsivity | Note 6 | | 96 | | | 24 | | mV/ (μW/ cm ²) | |
| Vos | Extrapolated offset voltage | Note 6 | -0.02 | 0.03 | 0.08 | -0.02 | 0.03 | 80.0 | V | |
| V_{d} | Dark voltage | $E_e = 0$ | 0 | | 0.08 | 0 | | 0.08 | V | |
| | Cumplication | $E_e = 20.5 \mu\text{W/cm}^2$ | | 1.1 | 1.7 | | | | A | |
| I _D | Supply current | $E_e = 83 \mu W/cm^2$ | | | <u>-</u> | | 1.1 | 1.7 | mA | |

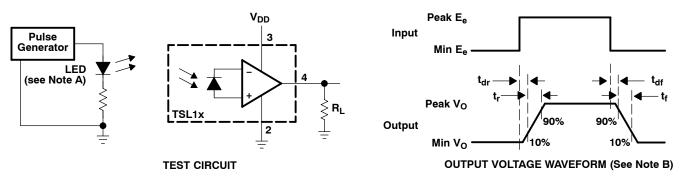
- NOTES: 3. Measurements are made with R_L = 10 k Ω between output and ground.
 - 4. Optical measurements are made using small-angle incident radiation from an LED optical source.
 - 5. The 640 nm input irradiance E_e is supplied by an AlInGaP LED with peak wavelength λ_p = 640 nm.
 - 6. Irradiance responsivity is characterized over the range $V_O = 0.2$ to 4 V. The best-fit straight line of Output Voltage V_O versus irradiance E_e over this range may have a positive or negative extrapolated V_O value for $E_e = 0$. For low irradiance values, the output voltage V_O versus irradiance E_e characteristic is non linear with a deviation toward $V_O = 0$, $E_e = 0$ origin from the best-fit straight line referenced above.

Dynamic Characteristics at V_{DD} = 5 V, T_A = 25°C, λ_p = 640 nm, R_L = 10 k Ω (unless otherwise noted) (see Figure 1)

| DADAMETER | | TEST SOMBITIONS | TSL12T | | TSL13T | | | | | |
|-----------------|---|------------------------------------|--------|-----|--------|-----|-----|-----|------|--|
| | PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | MIN | TYP | MAX | UNIT | |
| | Output pulse delay time for rising edge (0% | $Min V_O = 0 V; Peak V_O = 2 V$ | | 13 | | | 1.7 | | | |
| τ _{dr} | to 10%) | $Min V_O = 0.5 V; Peak V_O = 2 V$ | | 2.3 | | | 1.2 | | μS | |
| | O to to the contract (400/ to 000/) | $Min V_O = 0 V; Peak V_O = 2 V$ | | 20 | | | 7.2 | | | |
| t _r | Output pulse rise time (10% to 90%) | $Min V_O = 0.5 V; Peak V_O = 2 V$ | | 10 | | | 6.5 | | μS | |
| | Output pulse delay time for falling edge | $Min V_O = 0 V; Peak V_O = 2 V$ | | 2.3 | | | 1.2 | | | |
| t _{df} | (100% to 90%) | $Min V_O = 0.5 V; Peak V_O = 2 V$ | | 2.2 | | | 1.1 | | μS | |
| | O to the fell time (000) to 100() | Min $V_O = 0 V$; Peak $V_O = 2 V$ | | 10 | | | 6.8 | | | |
| t _f | Output pulse fall time (90% to 10%) | $Min V_O = 0.5 V; Peak V_O = 2 V$ | | 9 | | | 6.4 | | μS | |



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input irradiance is supplied by a pulsed AlInGaP light-emitting diode with the following characteristics: λ_p = 640 nm, $t_r < 1 \ \mu s$.
 - B. The output waveform is monitored on an oscilloscope with the following characteristics: $t_r < 100 \text{ ns}, Z_i \ge 1 \text{ M}\Omega, C_i \le 20 \text{ pF}.$

Figure 1. Switching Times

TYPICAL CHARACTERISTICS

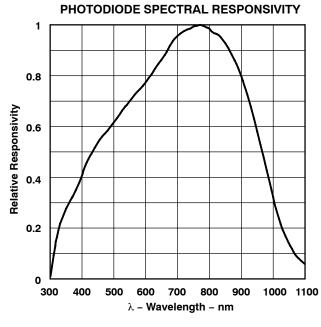


Figure 2

TSL12T

RISING EDGE DYNAMIC CHARACTERISTICS

PEAK OUTPUT VOLTAGE

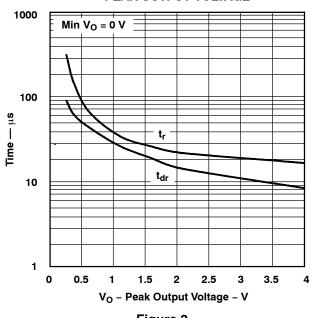


Figure 3

RISING EDGE DYNAMIC CHARACTERISTICS vs.

PEAK OUTPUT VOLTAGE

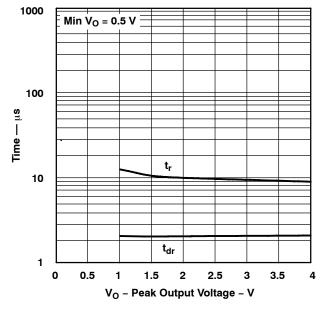


Figure 4

FALLING EDGE DYNAMIC CHARACTERISTICS vs.

PEAK OUTPUT VOLTAGE

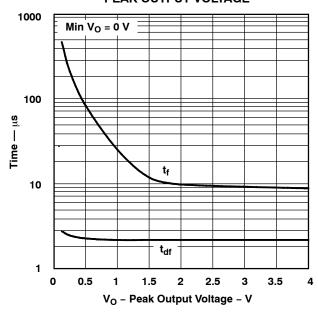


Figure 5

FALLING EDGE DYNAMIC CHARACTERISTICS vs.

PEAK OUTPUT VOLTAGE

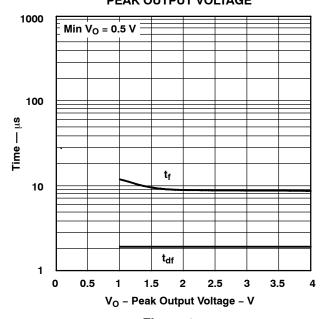
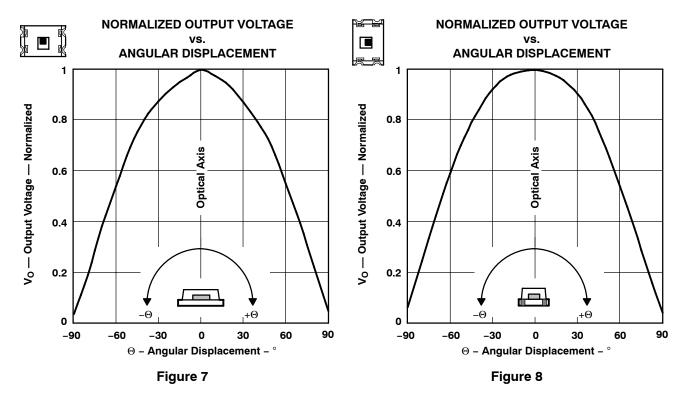


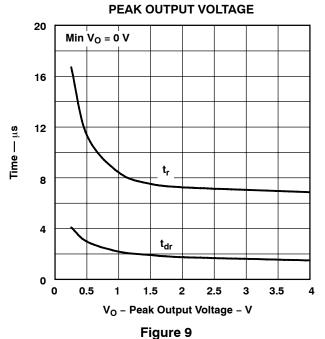
Figure 6

TSL12T



TSL13T

RISING EDGE DYNAMIC CHARACTERISTICS vs.



FALLING EDGE DYNAMIC CHARACTERISTICS vs.

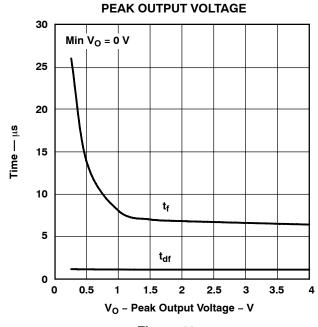


Figure 11

RISING EDGE DYNAMIC CHARACTERISTICS vs. PEAK OUTPUT VOLTAGE

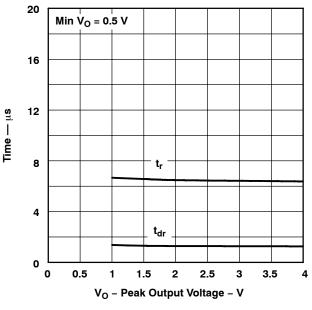


Figure 10

FALLING EDGE DYNAMIC CHARACTERISTICS vs.

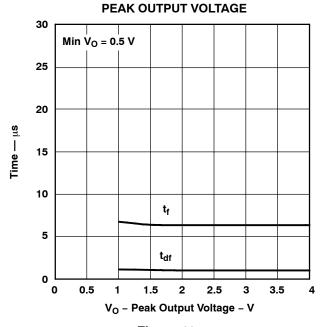
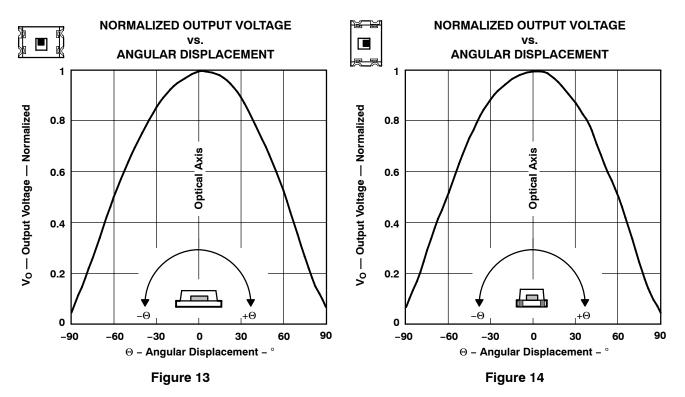


Figure 12

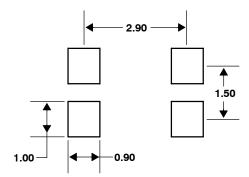
TSL13T



APPLICATION INFORMATION

PCB Pad Layout

Suggested PCB pad layout guidelines for the T package are shown in Figure 15.



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

Figure 15. Suggested T Package PCB Layout

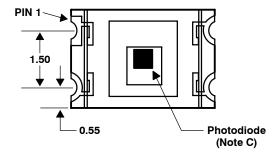
MECHANICAL DATA

The TSL12T and TSL13T are supplied in a low-profile surface-mount package. This package contains no lead (Pb).

PACKAGE T

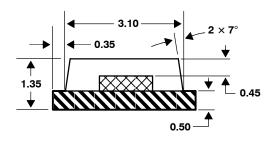
Four-Lead Surface Mount Device

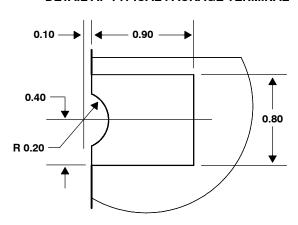
TOP VIEW



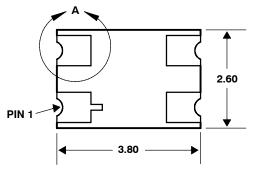
DETAIL A: TYPICAL PACKAGE TERMINAL

SIDE VIEW





BOTTOM VIEW





NOTES: A. All linear dimensions are in millimeters.

- B. Terminal finish is gold.
- C. The center of the 0.50 mm × 0.50 mm integrated photodiode active area is typically located in the center of the package.
- D. Dimension tolerance is \pm 0.15 mm.
- E. This drawing is subject to change without notice.

Figure 16. Package T — Four-Lead Surface Mount Device Packaging Configuration

MECHANICAL DATA 0.30 ± 0.050 2.10 **SIDE VIEW** 1.75 ± 0.100 Ø 1.50 4 ± 0.100 **END VIEW** 2 ± 0.100 8 Тур 0 Ф **TOP VIEW** 12 ± 0.100 φ 0 ф Θ 5.50 ± 0.100 R 0.20 TYP Ø 1.50 **DETAIL B DETAIL A** $2.90 \pm 0.100 A_{0}$ 3.09 MAX R 0.20 TYP **R 0.20 TYP** 4.29 MAX 4.10 ± 0.100 B₀ 1.80 K_o

- NOTES: A. All linear dimensions are in millimeters.
 - B. The dimensions on this drawing are for illustrative purposes only. Dimensions of an actual carrier may vary slightly.
 - C. Symbols on drawing A_0 , B_0 , and K_0 are defined in ANSI EIA Standard 481–B 2001.
 - D. Each reel is 178 millimeters in diameter and contains 1000 parts.
 - E. TAOS packaging tape and reel conform to the requirements of EIA Standard 481-B.
 - F. In accordance with EIA standard, device pin 1 is located next to the sprocket holes in the tape.
 - G. This drawing is subject to change without notice.

Figure 17. Four Lead Surface Mount Package Carrier Tape



MANUFACTURING INFORMATION

The reflow profile specified here describes expected maximum heat exposure of devices during the solder reflow process of the device on a PWB. Temperature is measured at the top of the device. Devices should be limited to one pass through the solder reflow profile.

Table 1. TSL12T, TSL13T Solder Reflow Profile

| PARAMETER | REFERENCE | TSL12T, TSL13T |
|---|-------------------|--------------------|
| Average temperature gradient in preheating | | 2.5°C/sec |
| Soak time | t _{soak} | 2 to 3 minutes |
| Time above T ₁ , 217°C | t ₁ | Max 60 sec |
| Time above T ₂ , 230°C | t ₂ | Max 50 sec |
| Time above T ₃ , (T _{peak} -10°C) | t ₃ | Max 10 sec |
| Peak temperature in reflow | T _{peak} | 260° C (-0°C/+5°C) |
| Temperature gradient in cooling | | Max -5°C/sec |

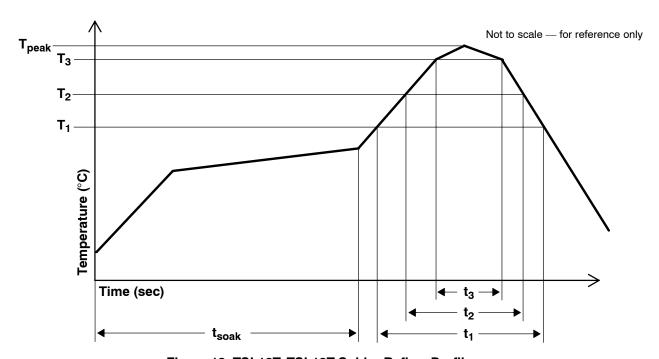


Figure 18. TSL12T, TSL13T Solder Reflow Profile

MANUFACTURING INFORMATION

Moisture Sensitivity

Optical characteristics of the device can be adversely affected during the soldering process by the release and vaporization of moisture that has been previously absorbed into the package molding compound. To ensure the package molding compound contains the smallest amount of absorbed moisture possible, each device is dry–baked prior to being packed for shipping. Devices are packed in a sealed aluminized envelope with silica gel to protect them from ambient moisture during shipping, handling, and storage before use.

This package has been assigned a moisture sensitivity level of MSL 3 and the devices should be stored under the following conditions:

Temperature Range 5°C to 50°C Relative Humidity 60% maximum

Total Time 6 months from the date code on the aluminized envelope — if unopened

Opened Time 168 hours or fewer

Rebaking will be required if the devices have been stored unopened for more than 6 months or if the aluminized envelope has been open for more than 168 hours. If rebaking is required, it should be done at 90°C for 4 hours.



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